1 Electrical characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25$ °C)

Symbol	Parameter and test conditions	Value	Unit
V _{PP}	Internal pins (A3, B3, C3): ESD discharge IEC 61000-4-2, air discharge ESD discharge IEC 61000-4-2, contact discharge External pins (A2, B1, C2, C1): ESD discharge IEC 61000-4-2, air discharge ESD discharge IEC 61000-4-2, contact discharge	2 2 15 8	kV
T _j	Maximum junction temperature	125	°C
T _{op}	Operating temperature range	-40 to +85	°C
T _{stg}	Storage temperature range	-55 to 150	°C

Figure 3. Electrical characteristics (definitions)

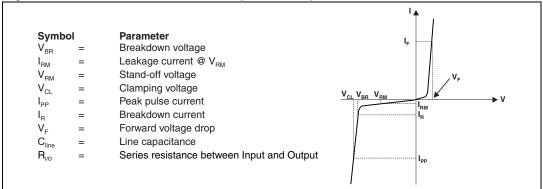


Table 2. Electrical characteristics ($T_{amb} = 25$ °C)

Symbol	Test conditions	Min.	Тур.	Max.	Unit
V_{BR}	I _R = 1 mA	6	-	20	V
I _{RM}	V _{RM} = 3 V	-	-	0.2	μA
R_d		-	1.5	-	Ω
R _{1,} R ₃	Tolerance ± 20%	-	100	-	Ω
R ₂	Tolerance ± 20%	-	47	-	Ω
C _{line}	$V_{line} = 0 \text{ V}, V_{osc} = 30 \text{ mV}, F = 1 \text{ MHz}$	-	-	20	pF

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Figure 4. S21 (dB) attenuation measurement Figure 5. S21 (dB) attenuation measurement (A2-A3 line) S21 (dB) attenuation measurement (B1-B3 line)

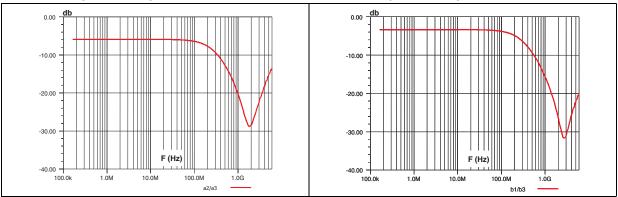


Figure 6. S21 (dB) attenuation measurement Figure 7. Analog crosstalk measurements (C1-C3 line)

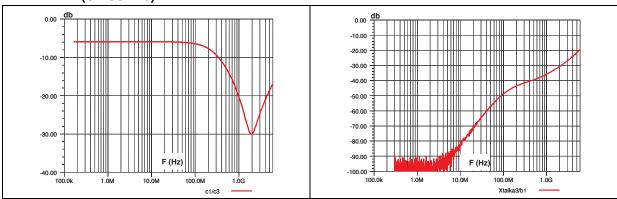
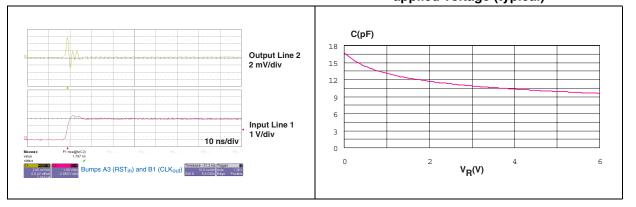


Figure 8. Digital crosstalk measurements

Figure 9. Line capacitance versus reverse applied voltage (typical)



Aplac model EMIF03-SIM02F3

2 Aplac model

Figure 10. Aplac model

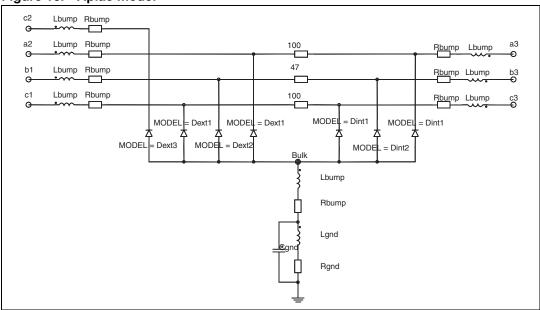


Figure 11. Aplac parameters

aplacvar Rs 150m	Dint1	Dext1	Dint2	Dext2	Dext3
aplacvar Cext1 12pF	BV=15	BV=15	BV=15	BV=15	BV=15
		20			
aplacvar Cext2 14pF	CJO=Cint1	CJO=Cext1	CJO=Cint2	CJO=Cext2	CJO=Cext3
aplacvar Cext3 18pF	IBV=1u	IBV=1u	IBV=1u	IBV=1u	IBV=1u
aplacvar Cint1 4.5pF	IKF=1000	IKF=1000	IKF=1000	IKF=1000	IKF=1000
aplacvar Cint2 4pF	IS=10f	IS=10f	IS=10f	IS=10f	IS=10f
aplacvar Rbump 17m	ISR=100p	ISR=100p	ISR=100p	ISR=100p	ISR=100p
aplacvar Lbump 43pH	N=1	N=1	N=1	N=1	N=1
aplacvar Rgnd 500m	M=0.3333	M=0.3333	M=0.3333	M=0.3333	M=0.3333
aplacvar Lgnd 50pH	RS=0.29	RS=0.25	RS=0.31	RS=0.28	RS=0.25
aplacvar Cgnd 0.15pF	VJ=0.6	VJ=0.6	VJ=0.6	VJ=0.6	VJ=0.6
aplacvar Rsub 100m	TT=50n	TT=50n	TT=50n	TT=50n	TT=50n

EMIF03-SIM02F3 Aplac model

Figure 12. Voltages when IEC 61000-4-2 (+15 kV air discharge) applied to external pin

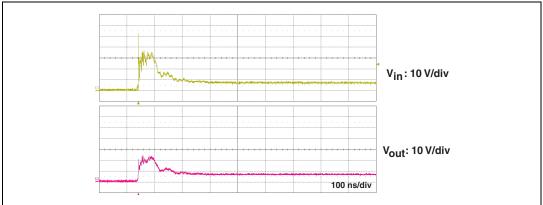
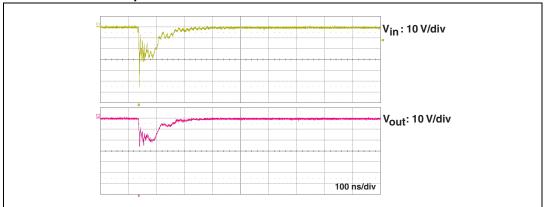
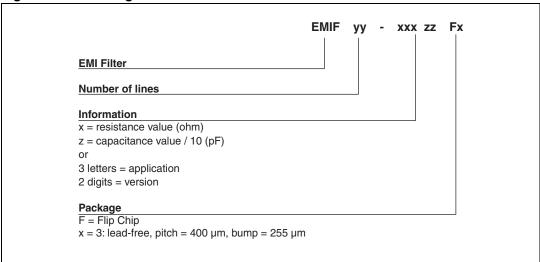


Figure 13. Voltages when IEC 61000-4-2 (- 15 kV air discharge) applied to external pin



3 Ordering information scheme

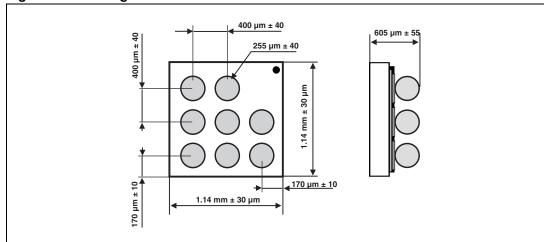
Figure 14. Ordering information scheme



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 15. Package dimensions



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Figure 16. Footprint

Figure 17. Marking

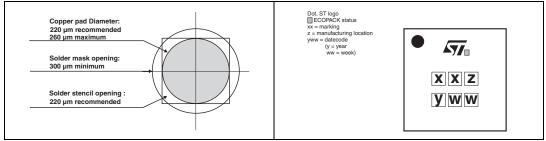
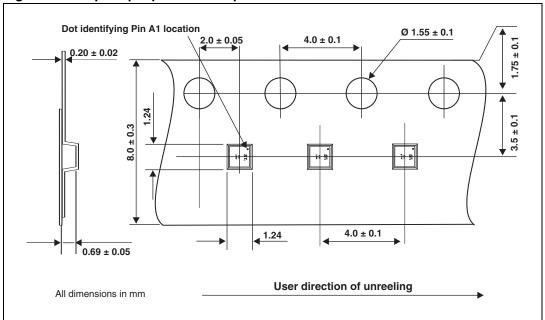


Figure 18. Flip Chip tape and reel specification



Ordering information 5

Ordering information Table 3.

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF03-SIM02F3	НА	Flip Chip	1.74 mg	5000	Tape and reel 7"

Note:

More information is available in the application notes:

AN2348: "STMicroelectronics 400 micro-metre Flip Chip: package description and

recommendation for use"

AN1751: "EMI filters: recommendations and measurements"

Revision history EMIF03-SIM02F3

6 Revision history

Table 4. Document revision history

Date	Revision	Changes
19-Jul-2005	1	Initial release.
26-Feb-2007	2	Changed out to ext in Configuration diagram on page 1. Added Ecopack statement. Reformatted to current layour standard. Updated Application note AN2348 reference and description.
28-Nov-2007	3	Updated ECOPACK statement. Updated Figure 14, Figure 15, Figure 16 and Figure 18. Reformatted to current standards.
09-Feb-2010	4	Updated die dimensions in <i>Figure 15</i> and pocket dimensions in <i>Figure 18</i> .
07-Apr-2010	5	Updated tolerance dimensions in Figure 15: Package dimensions.

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